# 826469-8 - ACTIVE

### AMPMODU | AMPMODU Headers

TE Internal #: 826469-8 PCB Mount Header, Vertical, Board-to-Board, 16 Position, 2.54 mm [.1 in] Centerline, Partially Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

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#### Connectors > PCB Connectors > PCB Headers & Receptacles



### PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **16** 

Number of Rows: 2

### Features

### Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Partially Shrouded



Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	16
Number of Rows	2
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Insulation Resistance	5000 ΜΩ
Dielectric Withstanding Voltage (Max)	750 Vrms
Body Features	
Connector Profile	Standard
Primary Product Color	Black
Contact Features	

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	01/12/202
Operation/Application	
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Housing Temperature Rating	High
Jsage Conditions	
PCB Thickness (Recommended)	1.57 mm[.062 in]
Row-to-Row Spacing	2.54 mm[.1 in]
Dimensions	
Housing Material	PCT
Centerline (Pitch)	2.54 mm[.1 in]
lousing Features	
Connector Mounting Type	Board Mount
PCB Mount Alignment	Without
PCB Mount Retention	Without
Mating Alignment Type	Polarization
Mating Alignment	With
Mating Retention Type	Detent Latching
Mating Retention	With
Nechanical Attachment	
Termination Method to Printed Circuit Board	Through Hole - Solder
Termination Post & Tail Length	3.2 mm[.126 in]
Round Termination Post & Tail Diameter	.63 mm[.025 in]
Fermination Features	
Contact Current Rating (Max)	5 A
Contact Type	Pin
Contact Mating Area Plating Material Thickness	.8 μm[31.5 μin]
Contact Mating Area Plating Material	Gold
Contact Base Material	Phosphor Bronze
PCB Contact Termination Area Plating Material	Tin
Contact Underplating Material	Nickel
Contact Shape & Form	Round
Mating Pin Diameter	.63 mm[.025 in]

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Solder Process Feature	Board Standoff
Circuit Application	Signal
Industry Standards	
Agency/Standard	CSA, UL
Approved Standards	CSA LR7189, CUL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	200
Packaging Type	Box
Product Compliance For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE

2023 (235)

Does not contain REACH SVHC

Not Low Halogen - contains Br or Cl > 900 ppm.

Pin-in-Paste capable to 260°C

### Halogen Content

Solder Process Capability

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

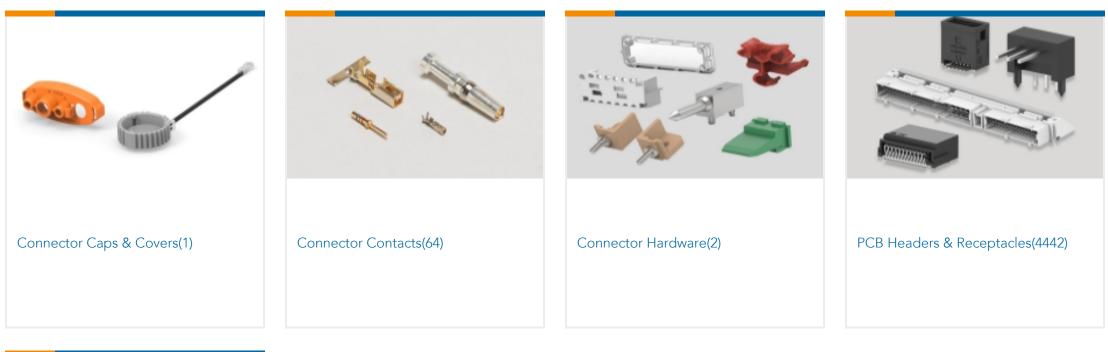
## **Compatible Parts**

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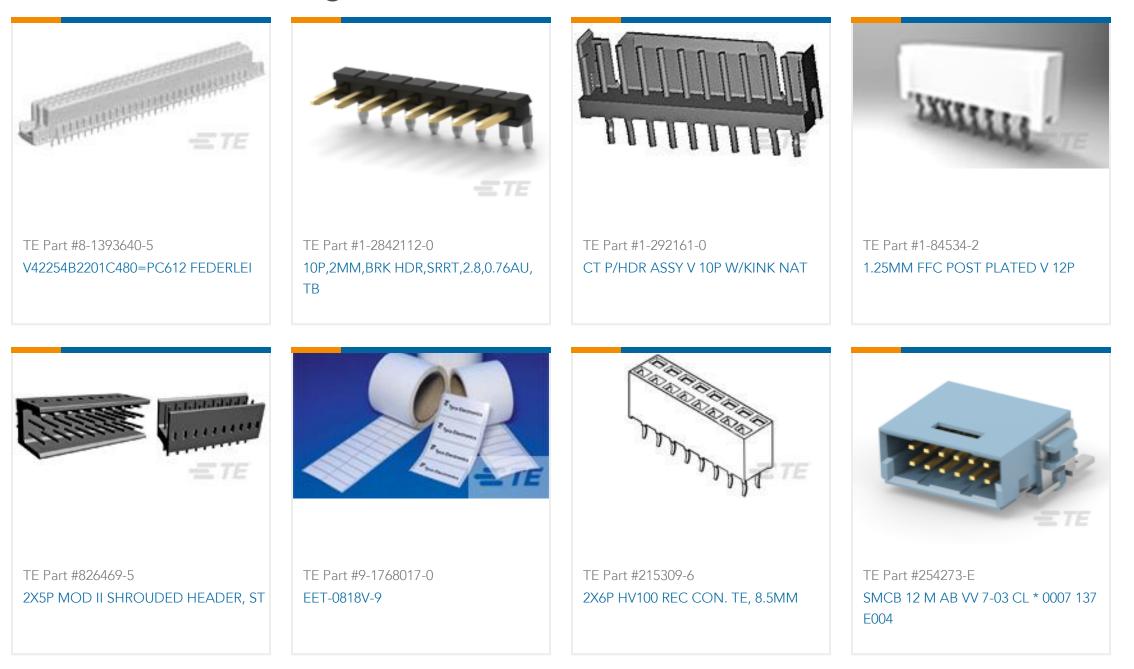
## Also in the Series AMPMODU Headers





Wire-to-Board Connector Assemblies & Housings(5)

## Customers Also Bought



PCB Mount Header, Vertical, Board-to-Board, 16 Position, 2.54 mm [.1 in] Centerline, Partially Shrouded, Gold, Through Hole - Solder, AMPMODU Headers





### Documents

### Product Drawings 2X8P MOD II SHROUDED HEADER, ST

English

#### **CAD** Files

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_826469-8\_E.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_826469-8\_E.3d\_igs.zip

English

Customer View Model

### ENG\_CVM\_CVM\_826469-8\_E.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Agency Approvals UL Report

English